Amtron Technology, Inc.

Industrial Grade 2.5" SATA III SSD AC Series Product Datasheet

V1.3

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1. INTRODUCTION

1.1. General Description

Amtron industrial grade AC series 2.5" SATA SSD delivers all the advantages of flash disk technology with Serial ATA I/II/III interface, with features of low power consumption and hot-swapping when removing, replacing, upgrading flash disks. The device is designed based on the standard 7-pin interface for data segment and 15-pin for power segment.

Amtron AC series 2.5" SATA SSDs are available in a wide range from 16GB up to 2TB. It can reach high performance of up to 550MB/s read and 500MB/s write speed.

1.2. Product Features

- 3D TLC NAND flash
- RoHS compliant [Lead free]
- Compliant with SATA Specification 3.2
- Compatible with SATA 1.5Gbps, 3Gbps and 6Gbps interface
- Support ATA-8 command set
- High speed:

Read: 550 MB/s max., Write: 500 MB/s max.

- Endure severe thermal and dynamic environments
 - Operation Temperature (Wide grade): -40°C to 85°C
 - Shock: 1500gVibration: 20g
- Very low power consumption
- MTBF: 3,000,000 hours
- Support S.M.A.R.T. Command
- Optional features
 - Power Loss Protection
- Controlled Bill of Materials (BOM)

1.3. Product Overview

Capacity

■ TLC: 120GB to 1920GB

pSLC: 20GB (16GB) to 640GB (512GB)

SATA Interface

■ SATA Revision 3.2

 SATA 1.5Gbps, 3Gbps, and 6Gbps interface

Flash Interface

Flash Type: 3D TLC

Performance

Read up to 550 MB/s

■ Write up to 500 MB/s

Power Consumption ²

Active mode: < 1,650 mW

■ Idle mode: < 330 mW

Low Power Management

■ DIPM/HIPM Mode

DEVSLP Mode (optional)

MTBF ¹

3,000,000 hours

Advanced Flash Management

Bad Block Management

■ TRIM

SMART

Over-Provision

Temperature Range

Operation (Standard): 0°C to 70°C

■ Operation (Wide): -40°C to 85°C

■ Storage: -40°C ~ 85°C

Optional Features

Power Loss Protection (PLP)

Advanced Encryption Standard (AES)

Thermal Sensor (T/S)

Write Protection

Quick Erase

DEVSLP

Compliant

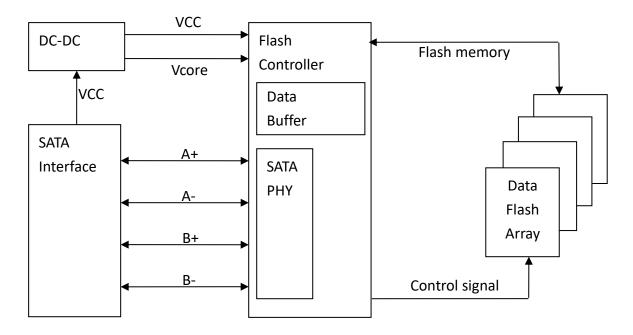
RoHS

■ CE & FCC

Notes:

- 1. MTBF, an acronym for Mean Time between Failures, is a measure of a device's reliability. Its value represents the average time between a repair and the next failure. The measure is typically in unit of hours. The higher the MTBF value, the higher the reliability of the product.
- 2. Please see Section 4.2 "Power Consumption" for details.

1.4. Block Diagram

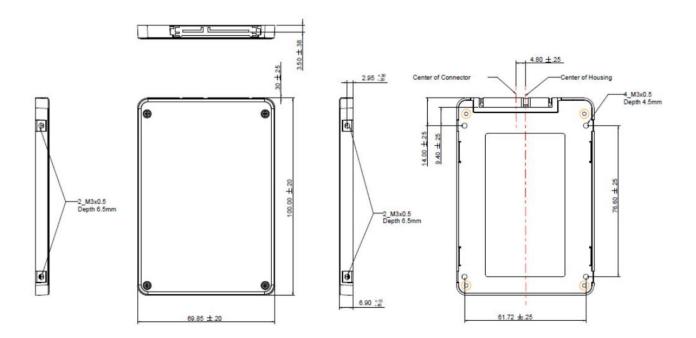


2.5" SATA SSD Block Diagram

2. PRODUCT SPECIFICATIONS

2.1. Product Dimension

Dimension: 100.00mm (L) x 69.85mm (W) x 6.90mm (H)



2.2. Capacity and Performance

Capacity

- TLC: 120GB up to 1,920GB (support 48-bit addressing mode)
- pSLC: 20GB(16GB) up to 640GB(512GB) (support 48-bit addressing mode)

• Electrical/Physical Interface

- SATA Interface
 - ◆ Compliant with SATA Revision 3.2
 - ♦ Compatible with SATA 1.5Gbps, 3Gbps and 6Gbps interface
 - ◆ Support ATA-8 command set

• Built-in 4-channel NAND flash interface controller

- Enhanced endurance by dynamic/static wear-leveling
- AgileECC 2 which includes:
 - ♦ Hardware-based V.P.R (Virtual Parity Recovery)
 - ♦ Support 2K Byte code-word length
 - ◆ Support Shift read/Read Retry feature of NAND flash
 - ♦ Read Disturb protection
 - Data integrity under power-cycling

Supported NAND Flash

- Support Toggle 2.0 and ONFi 4.0 all types of 3D-NAND, up to 667MHz
- Support SMART and TRIM commands
- Support Hardware Power Loss Protection (Optional)
- Support AES 256 bit
- Thermal Sensor

Capacity Information

Capacity	Cylinders	Heads	Sectors	Total Sectors	User Data Size
20GB	16,383	16	63	39,091,248	
40GB	16,383	16	63	78,161,328	
80GB	16,383	16	63	156,301,488	
120GB	16,383	16	63	234,441,648	Depended on file
160GB	16,383	16	63	312,581,808	management
240GB	16,383	16	63	468,862,128	
320GB	16,383	16	63	625,142,448	
480GB	16,383	16	63	937,703,088	

640GB	16,383	16	63	1,250,263,728
960GB	16,383	16	63	1,875,385,008
1,920GB	16,383	16	63	3,750,748,848

Performance

			ential
Capacity	Flash Type	Read	Write
		(MB/s)	(MB/s)
120GB	BiCS5, BGA, 512Gb	550	220
240GB	BiCS5, BGA, 512Gb	550	385
480GB	BiCS5, BGA, 512Gb	550	500
960GB	BiCS5, BGA, 512Gb	550	500
1,920GB	BiCS5, BGA, 512Gb	550	500
20GB	BiCS5 pSLC, BGA, 512Gb	280	270
40GB	BiCS5 pSLC, BGA, 512Gb	550	220
80GB	BiCS5 pSLC, BGA, 512Gb	550	400
160GB	BiCS5 pSLC, BGA, 512Gb	550	500
320GB	BiCS5 pSLC, BGA, 512Gb	550	500
640GB	BiCS5 pSLC, BGA, 512Gb	550	500

Notes:

- 1. The performance was estimated based on 3D NAND flash.
- 2. Performance may differ according to flash configuration and platform.
- 3. The table above is for reference only.

• TBW (Terabytes Written)

Capacity	Flash Type	TBW
120GB	BiCS5, BGA, 512Gb	270
240GB	BiCS5, BGA, 512Gb	540
480GB	BiCS5, BGA, 512Gb	1020
960GB	BiCS5, BGA, 512Gb	1400
1,920GB	BiCS5, BGA, 512Gb	2940
20GB	BiCS5 pSLC, BGA, 512Gb	1440
40GB	BiCS5 pSLC, BGA, 512Gb	3170
80GB	BiCS5 pSLC, BGA, 512Gb	6580
160GB	BiCS5 pSLC, BGA, 512Gb	13365
320GB	BiCS5 pSLC, BGA, 512Gb	26330
640GB	BiCS5 pSLC, BGA, 512Gb	45880

Notes:

- 1. Samples were built using 3D NAND flash.
- 2. The test followed JEDEC219A client endurance workload.
- 3. TBW may differ according to flash configuration and platform.
- 4. The endurance of SSD could be estimated based on user behavior, NAND endurance cycles, and write amplification factor. It is not guaranteed by flash vendor.

2.3. Feature Descriptions

2.3.1. Power Loss Protection (PLP)

If the voltage supply is cut, for instance, accidental power off or sudden blackout, the data would be shortly lost. To protect SSD data integrity from this disastrous scenario, Amtron has developed the hardware-based technology named PLP (Power Loss Protection). The PLP equips SSDs with tantalum capacitors that can deliver urgent power current so that the flash controller can take this extended moment to flush cached data and essential metadata into NAND Flash blocks.

In addition to tantalum capacitors which guarantee SSD data integrity, an inbuilt IC detector also serves the same purpose as well as ensures the stability of data transmission. The detector is designed to take proactive measures for the aforementioned disastrous scenario. When supply voltage drops below a minimum threshold, the detector will send out signals to the flash controller notifying it to stop operating to prevent poor performance or erratic operation. In the meanwhile, signals will also be sent to DRAM to have cached data flushed into NAND Flash blocks so as to avoid data loss, similar to the function performed by tantalum capacitors.

AC series SSD is equipped with tantalum capacitors which have lower power leakage, higher operating temperature and higher volume-efficiency (high capacitance in small volume) than many other types of capacitors. The compact size and the high reliability are ideal for embedded computing systems.

2.3.2. Advanced Encryption Standard (AES)

Advanced Encryption Standard (AES) is a specification for the encryption of electronic data. AES has been adopted by the U.S. government since 2001 to protect classified information and is now widely implemented in embedded computing applications. The AES algorithm used in software and hardware is symmetric so that encrypting/decrypting requires the same encryption key. Without the key, the encrypted data is inaccessible to ensure information security.

Notably in flash memory applications, AES 256-bit hardware encryption is the mainstream to protect sensitive or confidential data. The hardware encryption provides better performance, reliability, and security than software encryption. It uses a dedicated processor, which is built inside the controller, to process the encryption and decryption. This enormously shortens the processing time and makes it efficient.

2.3.3. Thermal Sensor (T/S)

Thermal Sensor is a digital temperature sensor with serial interface. By using a designated pin for transmission, storage device owners are able to read temperature data.

2.4. Compliance

- SATA III (SATA Rev. 3.2)
- Up to ATA/ATAPI-8 (Including S.M.A.R.T)

3. ENVIRONMENTAL SPECIFICATIONS

Parameter Type		Specifications			
Tomporaturo	Operation	0°C to 70°C (Standard); -40°C to 85°C (Wide)			
Temperature	Non-operational	-55°C to 100°C			
	Operation	7.69 GRMS, 20~2000 Hz/random (compliant			
Vibration	Operation	with MIL-STD-810G)			
Vibration	Non-operational	4.02 GRMS, 15~2000 Hz/random (compliant			
		with MIL-STD-810G)			
	Operation	Acceleration, 50(G)/11(ms)/half sine (compliant			
Shock	Operation	with MIL-STD-202G)			
SHOCK	Non aparational	Acceleration, 1500(G)/0.5(ms)/half sine			
	Non-operational	(compliant with MIL-STD-883K)			

3.1. Certification

- RoHS
- CE / FCC

4. ELECTRICAL SPECIFICATIONS



4.1. Supply Voltage

Parameter	Rating
Operating Voltage	5V , ±5%

4.2. Power Consumption

Capacity	Flash Type	Active	Idle
120GB	BiCS5, BGA, 512Gb	1,225	250
240GB	BiCS5, BGA, 512Gb	1,325	250
480GB	BiCS5, BGA, 512Gb	1,425	250
960GB	BiCS5, BGA, 512Gb	1,375	250
1,920GB	.,920GB BiCS5, BGA, 512Gb		250
20GB	BiCS5 pSLC, BGA, 512Gb	925	225
40GB	BiCS5 pSLC, BGA, 512Gb	1,275	250
80GB	BiCS5 pSLC, BGA, 512Gb	1,300	250
160GB	BiCS5 pSLC, BGA, 512Gb	1,650	300
320GB	BiCS5 pSLC, BGA, 512Gb	1,500	250
640GB	BiCS5 pSLC, BGA, 512Gb	1,425	275

Unit: mW

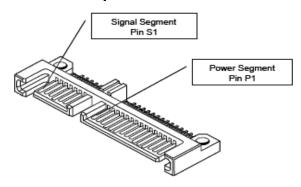
Notes:

- 1. The measured power voltage is 5V.
- 2. Samples were built using 3D NAND flash and measured under normal temperature.
- 3. Sequential R/W is measured while testing 1000MB sequential R/W 5 times by CyrstalDiskMark.
- 4. Power Consumption may differ according to flash configuration and platform.

5. INTERFACE



5.1. Pin Assignment and Descriptions



Sig As	Pin Number	Function
Signal Segment Pin Assignment	S1	GND
Se	S2	A+ (Differential Signal Pair A)
ent ent	S3	A – (Differential Signal Pair A)
ent	S4	GND
Pin	S5	B – (Differential Signal Pair B)
	S6	B+ (Differential Signal Pair B)
	S7	GND
	Pin Number	Function
	P1	Not Used (3.3V)
	P2	Not Used (3.3V)
Po	Р3	DEVSLP
We <u>r</u>	P4	GND
· Se	P5	GND
gm	P6	GND
ent	Р7	5V
Pin	P8	5V
Power Segment Pin Assignment	Р9	5V
sign	P10	GND
ıme	P11	Reserved for DAS LED
nt	P12	GND
	P13	Not Used (12V pre-charge)
	P14	Not Used (12V)
	P15	Not Used (12V)

6. SUPPORTED COMMANDS



6.1. ATA Command List

Op-C	Op-Code Command Description Op-Code		Command Description		
00h		NOP	60h		Read FPDMA Queued
06h		Data Set Management	61h		Write FPDMA Queued
10h		Recalibrate	70h		Seek
20h		Read Sectors	90h		Execute Device Diagnostic
21h		Read Sectors without Retry	91h		Initialize Device Parameters
24h		Read Sectors EXT	92h		Download Microcode
25h		Read DMA EXT	93h		Download Microcode DMA
27h		Read Native Max Address EXT	B0h		SMART
29h		Read Multiple EXT	B0h	D0h	SMART READ DATA
2Fh		Dood Log EVT	B0h	D1h	SMART READ DATA ATTRIBUTE
ZFII		Read Log EXT	BUII	DIII	THRESHOLD
30h		Write Sectors	B0h	D2h	SMART ENABLE/DISABLE ATTRIBUTE
3011		Write Sectors	ВОП	DZII	AUTOSAVE
31h		Write Sectors without Retry	B0h D3h		SMART SAVE ATTRIBUTE VALUES
34h		Write Sectors EXT	B0h	D4h	SMART EXECUTE OFF-LINE
3411				D411	IMMEDIATE
35h		Write DMA EXT	B0h	D5h	SMART READ LOG
37h		Set Native Max Address EXT	B0h	D6h	SMART WRITE LOG
39h		Write Multiple EXT	B0h	D8h	SMART ENABLE OPERATIONS
3Dh		Write DMA FUA EXT	B0h	D9h	SMART DISABLE OPERATIONS
3Fh		Write Long EXT	B0h	DAh	SMART RETURN STATUS
40h		Read Verify Sectors	B0h	DBh	SMART ENABLE/DISABLE
4011			BON DBN		AUTOMATIC OFF-LINE
41h		Read Verify Sectors without Retry	B1h		DEVICE CONFIGURATION OVERLAY
42h		Read Verify Sectors EXT	B1h	C0h	DEVICE CONFIGURATION RESTORE
45h		Write Uncorrectable EXT	B1h	C1h	DEVICE CONFIGURATION FREEZE
4311		Write Uncorrectable EXT	DIII	CIII	LOCK
47h		Read Log DMA EXT	B1h	C2h	DEVICE CONFIGURATION IDENTIFY
57h		Write Log DMA EXT	B1h C3h		DEVICE CONFIGURATION SET
B1h	C4h	DEVICE CONFIGURATION IDENTIFY DMA	A ECh		Identify Device
B1h	B1h C5h DEVICE CONFIGURATION SET DMA		EFh		Set Features
C4h		Read Multiple	EFh 02h		Enable 8-bit PIO transfer mode
Op-Code		Command Description	Op-Code		Command Description

Amtron Technology, Inc.

Industrial Grade AC series 2.5" SATA III SSD

					Set transfer mode based on value in
C5h	Write Multiple	EFh	03h		Count field
					Enable advanced power
C6h	Set Multiple Mode	EFh	05h		management
C8h	Read DMA	EFh	10h		Enable use of Serial ATA feature
C9h	Pood DMA without Potry	EFh	10h	02h	Enable DMA Setup FIS Auto-Activate
C9II	Read DMA without Retry	CFII	1011	0211	optimization
CAh	Write DMA	EFh	10h	03h	Enable Device-initiated interface
C/ 111	Wille Billin		1011	0311	power state (DIPM) transitions
CBh	Write DMA without Retry	EFh	10h	06h	Enable Software Settings
					Preservation (SSP)
CEh	Write Multiple FUA EXT	EFh	10h	07h	Enable Device Automatic Partial to
					Slumber transitions
E0h	Standby Immediate	EFh	10h	09h	Enable Device Sleep
E1h	Idle Immediate	EFh	55h		Disable read look-ahead feature
E2h	Standby	EFh	66h		Disable reverting to power-on
					defaults
E3h	n Idle EFh 82h		Disable write cache		
E4h	Read Buffer		85h		Disable advanced power
			90h		management
E5h	Check Power Mode	EFh	90h		Disable use of Serial ATA feature set
E6h	Sleep	EFh	90h	02h	Disable DMA Setup FIS Auto-Activate
					optimization
E7h	Flush Cache	EFh	90h	03h	Disable Device-initiated interface power state (DIPM) transitions
					Disable Software Settings
E8h	Write Buffer	EFh	90h	06h	Preservation (SSP)
					Disable Device Automatic Partial to
E9h	Read Buffer DMA	EFh	90h	07h	Slumber transitions
EAh	Flush Cache EXT	EFh	90h	09h	Disable Device Sleep
EBh	Write Buffer DMA	EFh	AAh	<u> </u>	Enable read look-ahead feature
EFh CCh				Security Erase Unit	
F1h	Security Set Password	F5h			Security Freeze Lock
F2h	Security Unlock	F6h			Security Disable Password
1		F8h			

6.2. Identify Device Data

The following table details the sector data returned by the IDENTIFY DEVICE command.

	F: Fixed	The sector data retain					
	V: Variable	5 6 1					
Word	X:	Default Value	Description				
	retired/obsolete						
	/reserved	22.42					
0	F	0040h	General configuration bit-significant information				
1	Х	*1	Obsolete – Number of logical cylinders				
2	F	C837h	Specific configuration				
3	Х	0010h	Obsolete – Number of logical heads (16)				
4-5	Х	00000000h	Retired				
6	X	003Fh	Obsolete – Number of logical sectors per logical track (63)				
7-8	X	00000000h	Reserved for assignment by the Compact Flash Association				
9	Х	0000h	Retired				
10-19	V	Varies	Serial number (20 ASCII characters)				
20-21	Х	0000h	Retired				
22	X	0000h	Obsolete				
23-26	V	Varies	Firmware revision (8 ASCII characters)				
27-46	V	Varies	Model number (xxxxxxxxx)				
7:0- Maximum r		8010h	7:0- Maximum number of sectors transferred per interrupt on				
		001011	MULTIPLE commands				
48	F	4000h	Reserved				
49	F	2F00h	Capabilities				
50	F	4000h	Capabilities				
51-52	X	000000000h	Obsolete				
53	F	0007h	Words 88 and 70:64 valid				
54	Х	*1	Obsolete – Number of logical cylinders				
55	Х	0010h	Obsolete – Number of logical heads (16)				
56	Х	003Fh	Obsolete – Number of logical sectors per track (63)				
57-58	Х	*2	Obsolete – Current capacity in sectors				
		0110	Number of sectors transferred per interrupt on MULTIPLE				
59	F 0110h		commands				
60-61	V	*3	Maximum number of sector (28bit LBA mode)				
62	Х	0000h	Obsolete				
63	F	0407h	Multi-word DMA modes supported/selected				

Word	F: Fixed V: Variable X: retired/obsolete /reserved	Default Value	Description	
64	F	0003h	PIO modes supported	
65	F	0078h	Minimum Multiword DMA transfer cycle time per word	
66	F	0078h	Manufacturer's recommended Multiword DMA transfer cycle time	
67	F	0078h	Minimum PIO transfer cycle time without flow control	
68	F	0078h	Minimum PIO transfer cycle time with IORDY flow control	
69	F	1F00h	Additional Supported	
70	Х	0000h	Reserved	
71-74	х	00000000000 0000h	Reserved for the IDENTIFY PACKET DEVICE command	
75	F	001Fh	Queue depth	
76	F	850Eh	Serial SATA capabilities	
77	F	0006h	Supported Serial ATA Phy speed	
78	F	004Ch	Serial ATA features supported	
79	F	0040H	Serial ATA features enabled	
80	F	0FF8h	Major Version Number	
81	F	0000h	Minor Version Number	
82	F	746Bh	Command set supported	
83	F	7D01h	Command set supported	
84	F	4163h	Command set/feature supported extension	
85	F	7469h	Command set/feature supported or enabled	
86	F	BC01h	Command set/feature supported or enabled	
87	F	4163h	Command set/feature supported or enabled	
88	F	007Fh	Ultra DMA Modes	
89	F	000Ah	Time required for Normal Erase mode SECURITY ERASE UNIT command	
90	F	001Eh	Time required for an Enhanced Erase mode SECURITY ERASE UNIT command	
91	F	0000h	Current advanced power management value	
92	F	FFFEh	Master Password Revision Code	
93	F	0000h	Hardware reset result. The contents of the bits (12:0) of this word can be changed only during the execution of hardware reset.	

Word	F: Fixed V: Variable X: retired/obsolete /reserved	Default Value	Description	
94	х	0000h	Vendor's recommended and actual acoustic management value	
95	F	0000h	Stream Minimum Request Size	
96	F	0000h	Streaming Transfer Time – DMA	
97	F	0000h	Streaming Access Latency – DMA and PIO	
98-99	F	0000h	Streaming Performance Granularity	
100-103	V	*4	Maximum user LBA for 48 bit Address feature set	
104	F	0000h	Streaming Transfer Time – PIO	
105	F	0008h	Maximum number of 512-byte blocks per DATA SET MANAGEMENT command	
106	F	4000h	Physical sector size/Logical sector size	
107	F	0000h	Inter-seek delay for ISO-7779 acoustic testing in microseconds	
108-111	F	Varies	Reserved	
112-115	х	00000000000 0000h	Reserved	
116	X	0000h	Reserved	
117-118	F	00000000h	Words per logical Sector	
119	F	401Ch	Supported settings	
120	F	401Ch	Command set/Feature Enabled/Supported	
121-126	X	0h	Reserved	
127	X	0h	Obsolete	
128	F	0021h	Security status	
129-159	V	Varies	Vendor specific	
160	X	0h	Compact Flash Association (CFA) power mode 1	
161-167	X	0h	Reserved for assignment by the CFA	
168	V	Varies	Device Nominal Form Factor	
169	F	0001h	DATA SET MANAGEMENT command is supported	
170-173	F	0h	Additional Product Identifier	
174-175	X	0h	Reserve	
176-205	F	0h	Current media serial number	
206	F	0039h	SCT Command Transport	

Word	F: Fixed V: Variable X: retired/obsolete /reserved	Default Value	Description	
207-208	Х	0h	Reserved	
209	F	4000h	Alignment of logical blocks within a physical block	
210-211	F	0000h	Write-Read-Verify Sector Count Mode 3 (not support)	
212-213	F	0000h	Write-Read-Verify Sector Count Mode 2 (not support)	
214-216	X	0000h	NV Cache relate (not support)	
217	F	0001h	Non-rotating media device	
218	X	0h	Reserved	
219	Х	0h	NV Cache relate (not support)	
220	V	V Oh Write read verify feature set current mode		
221	X	0h	Reserved	
222	F	10FFh	Transport major version number	
223	F	0h	Transport minor version number	
224-229	X	0h	reserved	
230-233	F	0h	Extend number of user addressable sectors	
234	F	0001h	Minimum number of 512-byte data blocks per DOWNLOAD MICROCODE command for mode 03h	
235	F	FFFEh	Maximum number of 512-byte data blocks per DOWNLOAD MICROCODE command for mode 03h	
236-242	Х	0h	Reserved	
243	Х	0000h	Reserved	
244-254	Х	0h	Reserved	
255	F	XXA5h XX is variable	Integrity word (Checksum and Signature)	

■ List of Device Identification for Each Capacity

Capacity	*1	*2	*3	*4
(GB)	(Word 1/Word 54)	(Word 57–58)	(Word 60–61)	(Word 100–103)
20	3FFFh	FBFC10h	2547C30h	2547C30h
40	3FFFh	FBFC10h	4A8A5B0h	4A8A5B0h
80	3FFFh	FBFC10h	950F8B0h	950F8B0h
120	3FFFh	FBFC10h	DF94BB0h	DF94BB0h
128	3FFFh	FBFC10h	EE7C2B0h	EE7C2B0h
160	3FFFh	FBFC10h	OFFFFFFFh	12A19EB0h
240	3FFFh	FBFC10h	OFFFFFF	1BF244B0h
256	3FFFh	FBFC10h	OFFFFFFFh	1DCF32B0h
320	3FFFh	FBFC10h	OFFFFFFFh	2542EAB0h
480	3FFFh	FBFC10h	OFFFFFFh	37E436B0h
512	3FFFh	FBFC10h	OFFFFFFFh	3B9E12B0h
640	3FFFh	FBFC10h	OFFFFFFFh	4A8582B0h
960	3FFFh	FBFC10h	OFFFFFFFh	6FC81AB0h
1024	3FFFh	FBFC10h	OFFFFFF	773BD2B0h
1920	3FFFh	FBFC10h	OFFFFFF	DF8FE2B0h
2048	3FFFh	FBFC10h	OFFFFFF	EE7752B0h

7. ACROMYM



The following table is to list out the acronyms that have been applied throughout the document.

Term	Definitions		
AES	Advanced Encryption Standard		
ATTO	Commercial performance benchmark application		
СС	Conformal Coating		
DEVSLP	Device Sleep Mode		
DIPM	Device initiated power management		
HIPM	Host initiated power management		
LBA	Logical block addressing		
МВ	Mega-byte		
MTBF	Mean time between failures		
NCQ Native command queue			
PLP	LP Power Loss Protection		
QEJ	Quick Erase Jumper		
SATA	Serial advanced technology attachment		
S.M.A.R.T. Self-monitoring, analysis and reporting technology			
SSD	Solid state disk		
T/S	Thermal sensor		
WP	Write Protection		

8. PART NUMBER DECODER

$SFD-2ACX^{1}X^{2}X^{3}X^{4}X^{5}X^{6}X^{7}X^{8}$

Item		Series	Capacity (Byte)	NAND Flash	Option
			X ¹ X ² X ³ X ⁴ X ⁵	X _e	X ⁷ X ⁸
SFD	2	AC	0020G 0040G 0080G 0160G 0320G 0640G 0120G 0240G 0480G 0960G 1920G	A: 3D TLC Standard (0°C to +70°C) B: 3D TLC Industrial (-40°C to +85°C) V: 3D pSLC Standard (0°C to +70°C) W: 3D pSLC Industrial (-40°C to +85°C)	

X^7X^8

Blank: Standard

PA: Power Loss Protection (PLP) + AES + T/S

PB: AES + T/S

PC: Write Protection (WP) + AES + T/S

PD: Quick Erase Jumper (QEJ) + AES + T/S

PE: Conformal Coating (CC) + AES + T/S

PF: CC + WP + AES + T/S

PG: CC + QEJ + AES + T/S

PH: PLP + CC + AES + T/S

PI: PLP + QEJ + AES + T/S

PJ: DEVSLP + AES + T/S

PK: PLP + WP + AES + T/S

PL: PLP + WP + CC + AES + T/S